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L7 and equation	3

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US Patents Full-Text Database
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<u>L8</u>	L7 and equation	3	<u>L8</u>
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<u>L6</u>	L5 and plasma	3	<u>L6</u>
<u>L5</u>	L3 and (atomic near2 percent)	4	<u>L5</u>
<u>L4</u>	L3 and (argon adj plasma)	2	<u>L4</u>
<u>L3</u>	L2 and magnesium	18	<u>L3</u>
<u>L2</u>	L1 and (copper adj alloy)	154	<u>L2</u>
<u>L1</u>	(thin adj film) near2 transistor	14127	<u>L1</u>

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1. Document ID: US 6686661 B1

L8: Entry 1 of 3

File: USPT

Feb 3, 2004

US-PAT-NO: 6686661

DOCUMENT-IDENTIFIER: US 6686661 B1

TITLE: Thin film transistor having a copper alloy wire

2. Document ID: US 6413589 B1

L8: Entry 2 of 3

File: USPT

Jul 2, 2002

US-PAT-NO: 6413589

DOCUMENT-IDENTIFIER: US 6413589 B1

TITLE: Ceramic coating method

3. Document ID: US 5021401 A

L8: Entry 3 of 3

File: USPT

Jun 4, 1991

US-PAT-NO: 5021401

DOCUMENT-IDENTIFIER: US 5021401 A

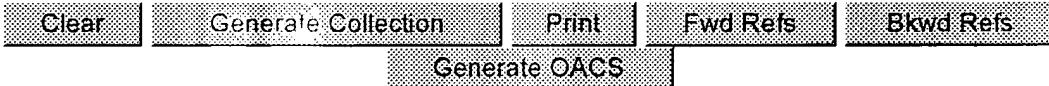
TITLE: Integrated production of superconductor insulation for chemical vapor deposition of nickel carbonyl

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1. Document ID: US 6743716 B2

L7: Entry 1 of 6

File: USPT

Jun 1, 2004

US-PAT-NO: 6743716

DOCUMENT-IDENTIFIER: US 6743716 B2

TITLE: Structures and methods to enhance copper metallization



2. Document ID: US 6686661 B1

L7: Entry 2 of 6

File: USPT

Feb 3, 2004

US-PAT-NO: 6686661

DOCUMENT-IDENTIFIER: US 6686661 B1

TITLE: Thin film transistor having a copper alloy wire



3. Document ID: US 6420262 B1

L7: Entry 3 of 6

File: USPT

Jul 16, 2002

US-PAT-NO: 6420262

DOCUMENT-IDENTIFIER: US 6420262 B1

TITLE: Structures and methods to enhance copper metallization



4. Document ID: US 6413589 B1

L7: Entry 4 of 6

File: USPT

Jul 2, 2002

US-PAT-NO: 6413589

DOCUMENT-IDENTIFIER: US 6413589 B1

TITLE: Ceramic coating method

[Full](#) | [Title](#) | [Citation](#) | [Front](#) | [Refer](#) | [Classification](#) | [Date](#) | [Reference](#) | [Claims](#) | [KWM](#) | [Drawn](#)

5. Document ID: US 5694184 A

L7: Entry 5 of 6

File: USPT

Dec 2, 1997

US-PAT-NO: 5694184

DOCUMENT-IDENTIFIER: US 5694184 A

TITLE: Liquid crystal display device

[Full](#) | [Title](#) | [Citation](#) | [Front](#) | [Refer](#) | [Classification](#) | [Date](#) | [Reference](#) | [Claims](#) | [KWM](#) | [Drawn](#)

6. Document ID: US 5021401 A

L7: Entry 6 of 6

File: USPT

Jun 4, 1991

US-PAT-NO: 5021401

DOCUMENT-IDENTIFIER: US 5021401 A

TITLE: Integrated production of superconductor insulation for chemical vapor deposition of nickel carbonyl

[Full](#) | [Title](#) | [Citation](#) | [Front](#) | [Refer](#) | [Classification](#) | [Date](#) | [Reference](#) | [Claims](#) | [KWM](#) | [Drawn](#)

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1. Document ID: US 6743716 B2

L5: Entry 1 of 4

File: USPT

Jun 1, 2004

US-PAT-NO: 6743716

DOCUMENT-IDENTIFIER: US 6743716 B2

TITLE: Structures and methods to enhance copper metallization

[Full](#) | [Title](#) | [Citation](#) | [Non-patent](#) | [Classification](#) | [Date](#) | [Reference](#) | [Links](#) | [Claims](#) | [KMC](#) | [Drawn D](#)

2. Document ID: US 6686661 B1

L5: Entry 2 of 4

File: USPT

Feb 3, 2004

US-PAT-NO: 6686661

DOCUMENT-IDENTIFIER: US 6686661 B1

TITLE: Thin film transistor having a copper alloy wire[Full](#) | [Title](#) | [Citation](#) | [Non-patent](#) | [Classification](#) | [Date](#) | [Reference](#) | [Links](#) | [Claims](#) | [KMC](#) | [Drawn D](#)

3. Document ID: US 6541858 B1

L5: Entry 3 of 4

File: USPT

Apr 1, 2003

US-PAT-NO: 6541858

DOCUMENT-IDENTIFIER: US 6541858 B1

TITLE: Interconnect alloy and methods and apparatus using same

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4. Document ID: US 6420262 B1

L5: Entry 4 of 4

File: USPT

Jul 16, 2002

US-PAT-NO: 6420262

DOCUMENT-IDENTIFIER: US 6420262 B1

TITLE: Structures and methods to enhance copper metallization

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1. Document ID: US 6495878 B1

L4: Entry 1 of 2

File: USPT

Dec 17, 2002

US-PAT-NO: 6495878

DOCUMENT-IDENTIFIER: US 6495878 B1

TITLE: Interlayer oxide layer having thin films for high dielectric constant application

Full	Title	Citation	Abstract	Specification	Dates	Reference	Claims	KMC	Drawn De
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2. Document ID: US 5796121 A

L4: Entry 2 of 2

File: USPT

Aug 18, 1998

US-PAT-NO: 5796121

DOCUMENT-IDENTIFIER: US 5796121 A

TITLE: Thin film traps for micro fabricated on plastic substrates

Full	Title	Citation	Abstract	Specification	Dates	Reference	Claims	KMC	Drawn De
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L3 and (argon adj plasma)	2
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